

Pb RoHS

General Description

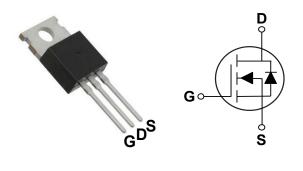
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BV _{DSS}	R _{DS(ON)}	I _D
200 V	20 mΩ	75 A

Features

- $\bullet R_{DS(ON)} {\leq} 20 m \Omega @V_{GS} {=} 10 V$
- Fast Switching
- Green Device Available

TO-220 Pin Configuration



Applications

- Load Switch
- PWM Application
- Power Management

Absolute Maximum Ratings T _c =25°C unless otherwise noted						
Symbol	Parameter	Rating	Units			
V _{DS}	Drain-Source Voltage	200	V			
V _{GS}	Gate-Source Voltage	±30	V			
I _D	Drain Current – Continuous (T _A =25°C)	75	А			
I _{DM}	Drain Current – Pulsed (NOTE 1)	250	А			
EAS	Single Pulse Avalanche Energy (NOTE 2)	300	mJ			
P _D	Power Dissipation (T _C =25°C)	125	W			
TJ	Operating Junction Temperature Range	-55 to 150	°C			
T _{STG}	Storage Temperature Range	-55 to 150	°C			
Marking Code		NS020				

Thermal Characteristics					
Symbol Parameter Rating		Unit			
R _{eja}	Thermal Resistance Junction to Ambient	60	°C/W		
R _{eJC}	Thermal Resistance Junction to Case	1	°C/W		





Electrical Characteristics (T_J=25°C, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	200			V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =200V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} =±20V , V_{DS} =0V			±100	nA

On Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V , I _D =40A			20	mΩ
V _{GS(th)}	Gate Threshold Voltage	$V_{GS}=V_{DS}$, I _D =250uA	3.6		5.0	V

Dynamic and switching Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Qg	Total Gate Charge			85		
Q _{gs}	Gate-Source Charge	V_{DD} =100V , V_{GS} =10V , I_{D} =40A		15		nC
Q_gd	Gate-Drain Charge			25		
T _{d(on)}	Turn-On Delay Time	V _{DS} =50V , R _G =2.5Ω , I _D =40A , V _{GS} =10V		45		
T _r	Rise Time			70		nS
T _{d(off)}	Turn-Off Delay Time			110		115
T _f	Fall Time			90		
C _{iss}	Input Capacitance			7500		
C _{oss}	Output Capacitance	V _{DS} =25V , V _{GS} =0V , F=1MHz		500		pF
C _{rss}	Reverse Transfer Capacitance]		210		

Drain-Source Diode Characteristics and Ratings

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ا _s	Continuous Body Diode Current				75	А
I _{SM}	Pulsed Diode Forward Current				150	А
V_{SD}	Diode Forward Voltage	V _{GS} =0V , I _S =40A			1.2	V
t _{rr}	Reverse Recovery Time	V_{GS} =0V , I _S =30A , V _{DD} =50V ,		110		nS
Q _{rr}	Reverse Recovery Charge	dI _F /dt=100A/us		0.55		uC

NOTES :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.

2. The EAS data shows Max. rating .The test condition is V_{DD} =50V, L=0.3mH, R_G=25 Ω , V_{GS}=10V.

3. The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%.

4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



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Characteristics Curves

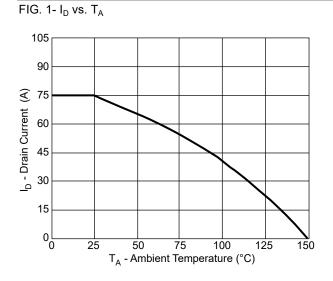
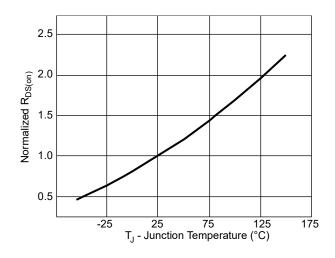


FIG. 3- Normalized $R_{\text{DS}(\text{ON})}$ vs. T_{J}





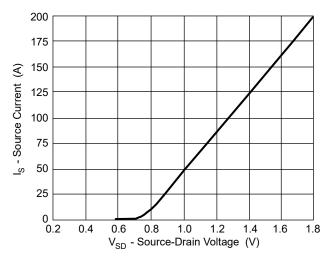


FIG. 2- Normalized BV_{DSS} vs. T_J

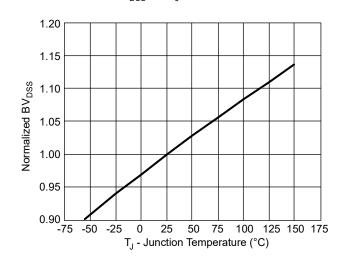


FIG. 4- Transfer Characteristics

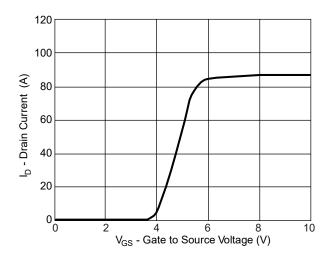
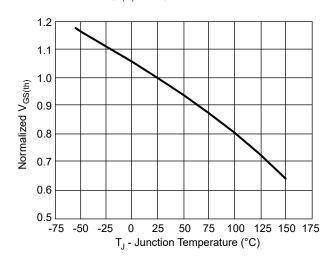


FIG. 6- Normalized $V_{GS(th)}$ vs. T_J





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Characteristics Curves

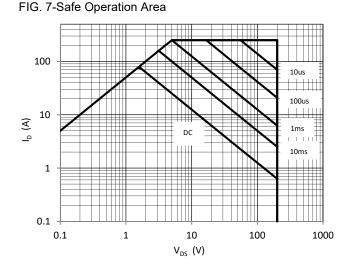
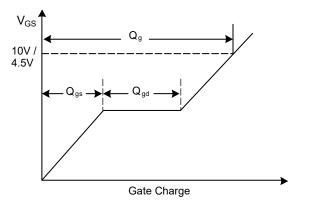
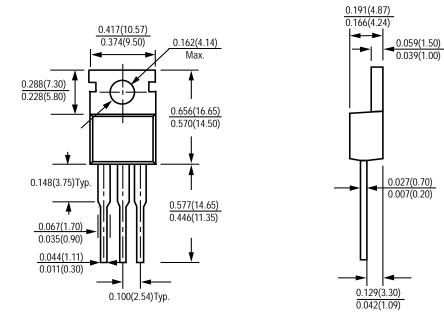


FIG. 9- Gate Charge Waveform

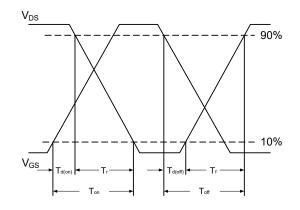


Package Outline Dimensions



TO-220 Dimensions in inches and (millimeters)

FIG. 8- Switching Time Waveform







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